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INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date (if appr priate)
TMW	5,028,560	07/02/91	Tsukamoto et al	437	239	
TMW	5,322,807	06/21/94	Chen et al	437	41TFT	08/19/92
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TMW	53-26584	03/11/78	Japan	437	21	Abstract	
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Examiner <i>TMWilezowski</i>	Date C nsid red <i>9/2000</i>
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*EXAMINER: Initial if citation considered, whether or not citation is in conformanc with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next c mmunication to applicant.